

WEST Search History

DATE: Tuesday, December 09, 2003

Set Name Query
side by side

Hit Count Set Name
result set

DB=USPT,JPAB,EPAB,DWPI,TDBD; THES=ASSIGNEE; PLUR=YES; OP=OR

L11	thermoelectric same protrusions	66	L11
L10	6452085.pn.	2	L10
L9	6524879.pn.	2	L9
L8	thermoelectric with (solder adj1 bumps)	9	L8

DB=JPAB,EPAB,DWPI; THES=ASSIGNEE; PLUR=YES; OP=OR

L7	thermoelectric adj1 device and (solder adj1 bumps)	0	L7
L6	thermoelectric adj1 device and protrusions	4	L6
L5	l1 and (solder adj1 bump)	0	L5
L4	l1 and protrusion	4	L4
L3	L1 and (support adj1 arms)	0	L3
L2	L1 and (semiconductor adj1 chips)	9	L2
L1	thermoelectric adj1 module	851	L1

END OF SEARCH HISTORY

L Number	Hits	Search Text	DB	Time stamp
1	3534	136/200-242.ccls.	USPAT	2003/12/09 09:26
2	4	136/200-242.ccls. and (solder adj1 bump)	USPAT	2003/12/09 09:42
3	7150	solder adj1 bump	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/12/09 09:42
4	3	(solder adj1 bump) same thermoelectric adj1 (module or device)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/12/09 09:46
5	10	(solder adj1 bump) same thermoelectric	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/12/09 09:48
6	397	136/200	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/12/09 10:04
7	612	136/201	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/12/09 10:22
8	463	136/203	USPAT	2003/12/09 10:40
9	267	136/242	USPAT	2003/12/09 10:52
10	143	257/930	USPAT	2003/12/09 10:57
11	623	257/53	USPAT	2003/12/09 11:03
12	251	438/55	USPAT	2003/12/09 11:10
13	202	438/54	USPAT	2003/12/09 11:10